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Materials Engineering—Select papers from Asia Conference on Mechanical and Materials Engineering (ACMME 2017)

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Deadline for manuscript
submissions:

closed (30 November 2017)

Message from the Guest Editors

Dear Colleagues,

The 2017, 5th Asia Conference on Mechanical and Materials Engineering (ACMME 2017) will be held at the University of Tokyo, Japan, 9–11 June, 2017. The aim of ACMME 2017 is to present the latest research and results from scientists in the fields related to Mechanical and Materials Engineering topics. This conference provides opportunities for delegates from different areas to exchange new ideas and application experiences, face-to-face, to establish business or research relationships and to find global partners for future collaboration. We hope that the conference results constitute a significant contribution to the knowledge in these up-to-date scientific fields.

Prof. Ching An Huang

Prof. Omar S. Es-Said

Guest Editors



mdpi.com/si/9699

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Message from the Editor-in-Chief

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